3.2x2.4mm SMD CHIP LED LAMP

Part Number: APD3224SYCK-F01

Super Bright Yellow

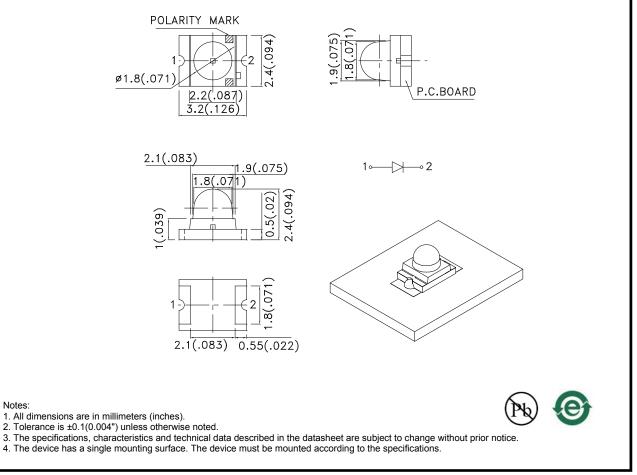
Features

- 3.2x2.4mm SMT LED, 2.4mm thickness.
- Low power consumption.
- Ideal for backlight and indicator.
- Various colors and lens types available.
- Package : 1500pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

The Super Bright Yellow device is made with AlGaInP (on GaAs substrate) light emitting diode chip.

Package Dimensions



Notes:

REV NO: V.5 CHECKED: Allen Liu DATE: JUL/27/2010 DRAWN: Y.H.Wu

PAGE: 1 OF 5 ERP: 1203001086

Selection Guide

Ocicotion Guide						_
Part No.	Part No. Dice		lv (mcd) [2] @ 20mA		Viewing Angle [1]	
			Min.	Тур.	201/2	
APD3224SYCK-F01	Super Bright Yellow (AlGaInP)	WATER CLEAR	800	1300	20°	

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions	
λpeak	Peak Wavelength	Super Bright Yellow	590		nm	I⊧=20mA	
λD [1]	Dominant Wavelength	Super Bright Yellow	590		nm	I⊧=20mA	
Δλ1/2	Spectral Line Half-width	Super Bright Yellow	20		nm	I⊧=20mA	
С	Capacitance	Super Bright Yellow	20		pF	VF=0V;f=1MHz	
VF [2]	Forward Voltage	Super Bright Yellow	2.0	2.5	V	I⊧=20mA	
IR	Reverse Current	Super Bright Yellow		10	uA	VR=5V	

Notes:

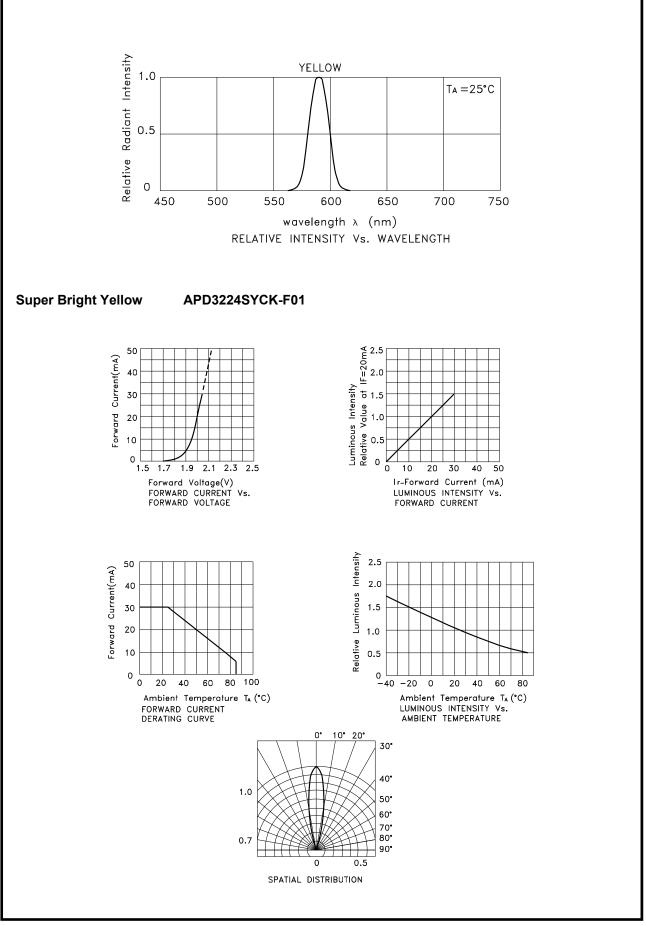
1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Super Bright Yellow	Units
Power dissipation	75	mW
DC Forward Current	30	mA
Peak Forward Current [1]	175	mA
Reverse Voltage	5	V
Operating Temperature	-40°C To +85°C	
Storage Temperature	-40°C To +85°C	

Note:

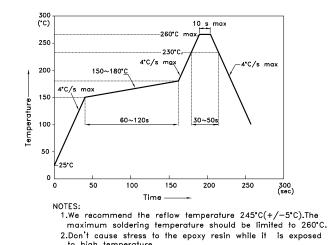
1. 1/10 Duty Cycle, 0.1ms Pulse Width.



APD3224SYCK-F01

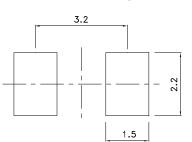
Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.

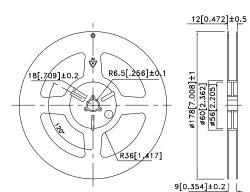


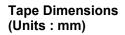
to high temperature. 3.Number of reflow process shall be 2 times or less.

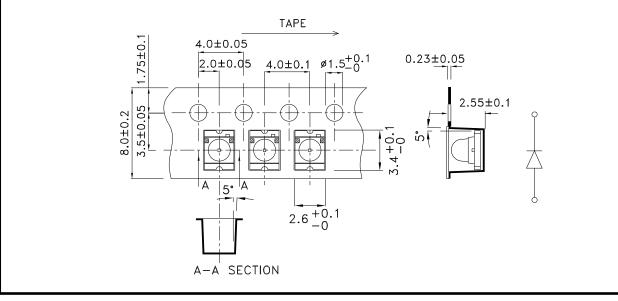
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)











REV NO: V.5 CHECKED: Allen Liu DATE: JUL/27/2010 DRAWN: Y.H.Wu

PAGE: 4 OF 5 ERP: 1203001086

